

September 1997 - Revised October 2003

## High-Speed CMOS Logic Dual Decade Ripple Counter

### Features

- Two BCD Decade or Bi-Quinary Counters
- One Package Can Be Configured to Divide-by-2, 4, 5, 10, 20, 25, 50 or 100
- Two Master Reset Inputs to Clear Each Decade Counter Individually
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- HCT Types
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Description

The CD74HC390 and 'HCT390 dual 4-bit decade ripple counters are high-speed silicon-gate CMOS devices and are pin compatible with low-power Schottky TTL (LSTTL). These devices are divided into four separately clocked sections. The counters have two divide-by-2 sections and two divide-by-5 sections. These sections are normally used in a BCD decade or bi-quinary configuration, since they share a common master reset (nMR). If the two master reset inputs (1MR and 2MR) are used to simultaneously clear all 8 bits of the counter, a number of counting configurations are possible within one package. The separate clock inputs (nCP0 and nCP1) of each section allow ripple counter or frequency division applications of divide-by-2, 4, 5, 10, 20, 25, 50 or 100. Each section is triggered by the High-to-Low transition of the input pulses (nCP0 and nCP1).

For BCD decade operation, the nQ0 output is connected to the nCP1 input of the divide-by-5 section. For bi-quinary decade operation, the nO3 output is connected to the nCP0 input and nQ0 becomes the decade output.

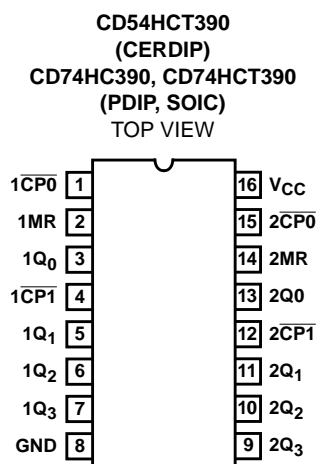
The master reset inputs (1MR and 2MR) are active-High asynchronous inputs to each decade counter which operates on the portion of the counter identified by the "1" and "2" prefixes in the pin configuration. A High level on the nMR input overrides the clock and sets the four outputs Low.

### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HCT390F3A	-55 to 125	16 Ld CERDIP
CD74HC390E	-55 to 125	16 Ld PDIP
CD74HC390M	-55 to 125	16 Ld SOIC
CD74HC390MT	-55 to 125	16 Ld SOIC
CD74HC390M96	-55 to 125	16 Ld SOIC
CD74HCT390E	-55 to 125	16 Ld PDIP
CD74HCT390M	-55 to 125	16 Ld SOIC
CD74HCT390MT	-55 to 125	16 Ld SOIC
CD74HCT390M96	-55 to 125	16 Ld SOIC

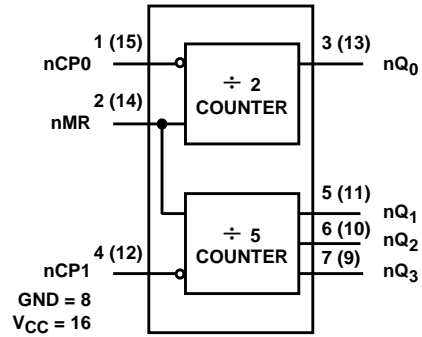
NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel. The suffix T denotes a small-quantity reel of 250.

### Pinout



**CD74HC390, CD54HCT390, CD74HCT390**

**Functional Diagram**



**TRUTH TABLE**

INPUTS		ACTION
CP	MR	
↑	L	No Change
↓	L	Count
X	H	All Qs Low

H = High Voltage Level, L = Low Voltage Level, X = Don't Care,  
 ↑ = Transition from Low to High Level, ↓ = Transition from High to Low.

**BCD COUNT SEQUENCE FOR 1/2 THE 390**

COUNT	OUTPUTS			
	Q0	Q1	Q2	Q3
0	L	L	L	L
1	H	L	L	L
2	L	H	L	L
3	H	H	L	L
4	L	L	H	L
5	H	L	H	L
6	L	H	H	L
7	H	H	H	L
8	L	L	L	H
9	H	L	L	H

Output nQ0 connected to nCP1 with counter input on nCP0.

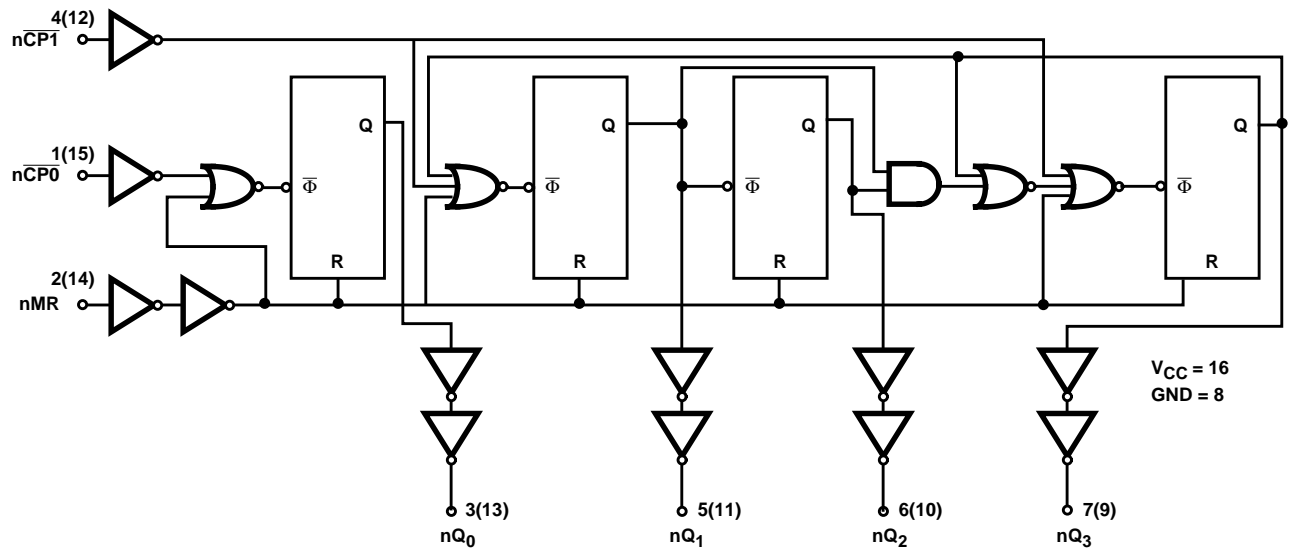
**B-QUINARY COUNT SEQUENCE FOR 1/2 THE 390**

COUNT	OUTPUTS			
	Q0	Q1	Q2	Q3
0	L	L	L	L
1	L	H	L	L
2	L	L	H	L
3	L	H	H	L
4	L	L	L	H
5	H	L	L	L
6	H	H	H	L
7	H	L	H	L
8	H	H	H	L
9	H	L	L	H

Output nQ3 connected to nCP0 with counter input on nCP1.

CD74HC390, CD54HCT390, CD74HCT390

Logic Diagram



# CD74HC390, CD54HCT390, CD74HCT390

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ (°C/W)
E (PDIP) Package .....	67
M (SOIC) Package .....	73
Maximum Junction Temperature .....	150°C
Maximum Storage Temperature Range .....	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) .....	300°C
(SOIC - Lead Tips Only)	

## Operating Conditions

Temperature Range ( $T_A$ ) .....	-55°C to 125°C
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	.4.5V to 5.5V
DC Input or Output Voltage, $V_I, V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V
			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	-	-	-	-	-	-	-	-	-	V
			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$
Quiescent Device Current	$I_{CC}$	$V_{CC}$ or GND	0	6	-	-	8	-	80	-	160	$\mu A$

**CD74HC390, CD54HCT390, CD74HCT390**

**DC Electrical Specifications (Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	0	5.5	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	8	-	80	-	160	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load	ΔI <sub>CC</sub> (Note 2)	V <sub>CC</sub> -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

**HCT Input Loading Table**

INPUT	UNIT LOADS
nCP0	0.45
nCP1, MR	0.6

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Table, e.g., 360μA max at 25°C.

**Prerequisite for Switching Specifications**

CHARACTERISTIC	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>										
Maximum Clock Frequency	f <sub>MAX</sub>	2	6	-	-	5	-	4	-	MHz
		4.5	30	-	-	24	-	20	-	MHz
		6	35	-	-	28	-	24	-	MHz
Clock Pulse Width, nCP0, nCP1	t <sub>w</sub>	2	80	-	-	100	-	120	-	ns
		4.5	16	-	-	20	-	24	-	ns
		6	14	-	-	17	-	20	-	ns

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**Prerequisite for Switching Specifications (Continued)**

CHARACTERISTIC	SYMBOL	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Reset Removal Time	t <sub>REM</sub>	2	70	-	-	90	-	105	-	ns
		4.5	14	-	-	18	-	21	-	ns
		6	12	-	-	15	-	18	-	ns
Reset Pulse Width	t <sub>W</sub>	2	50	-	-	65	-	75	-	ns
		4.5	10	-	-	13	-	15	-	ns
		6	9	-	-	11	-	13	-	ns

**HCT TYPES**

Maximum Clock Frequency	f <sub>MAX</sub>	4.5	27	-	-	22	-	18	-	MHz
Clock Pulse Width, nCP0, nCP1	t <sub>W</sub>	4.5	19	-	-	24	-	29	-	ns
Reset Removal Time	t <sub>REM</sub>	4.5	15	-	-	19	-	22	-	ns
Reset Pulse Width	t <sub>W</sub>	4.5	13	-	-	16	-	20	-	ns

**Switching Specifications** Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay (Figure 1) nCP0 to nQ0	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	175	-	220	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		C <sub>L</sub> = 15pF	5	-	14	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	30	-	37	-	45	ns
nCP1 to nQ1	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	185	-	230	-	280	ns
			4.5	-	-	37	-	46	-	56	ns
			6	-	-	31	-	39	-	48	ns
nCP1 to nQ2	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	245	-	305	-	370	ns
			4.5	-	-	49	-	61	-	74	ns
			6	-	-	42	-	52	-	63	ns
nCP1 to nQ3	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	180	-	225	-	270	ns
			4.5	-	-	36	-	45	-	54	ns
			5	-	15	-	-	-	-	-	ns
			6	-	-	31	-	38	-	46	ns
nCP0 to nQ3 (nQ0 connected to nCP1)	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	365	-	455	-	550	ns
			4.5	-	-	73	-	91	-	110	ns
			6	-	-	62	-	77	-	94	ns
MR to Q <sub>n</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	190	-	240	-	285	ns
			4.5	-	-	38	-	48	-	57	ns
		C <sub>L</sub> = 15pF	5	-	16	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	32	-	41	-	48	ns

## CD74HC390, CD54HCT390, CD74HCT390

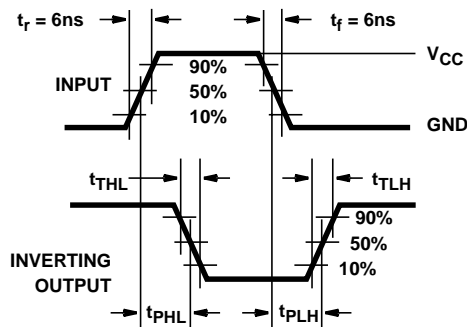
### Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Output Transition Time (Figure 1)	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	$C_{IN}$	$C_L = 50\text{pF}$	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	$C_L = 15\text{pF}$	5	-	28	-	-	-	-	-	pF
<b>HCT TYPES</b>											
Propagation Delay (Figure 1) $n\overline{CP0}$ to $nQ_0$	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	40	-	50	-	60	ns
		$C_L = 15\text{pF}$	5	-	17	-	-	-	-	-	ns
$n\overline{CP1}$ to $nQ_1$	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	43	-	51	-	65	ns
$n\overline{CP1}$ to $nQ_2$	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	55	-	69	-	83	ns
$n\overline{CP1}$ to $nQ_3$	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	42	-	53	-	63	ns
		$C_L = 15\text{pF}$	5	-	18	-	-	-	-	-	ns
$n\overline{CP0}$ to $nQ_2$ ( $nQ_0$ connected to $n\overline{CP1}$ )	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	84	-	105	-	126	ns
MR to $Q_n$	$t_{PLH}, t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	42	-	53	-	63	ns
		$C_L = 15\text{pF}$	5	-	18	-	-	-	-	-	ns
Output Transition	$t_{TLH}, t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	$C_{IN}$	$C_L = 15\text{pF}$	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	$C_L = 15\text{pF}$	5	-	32	-	-	-	-	-	pF

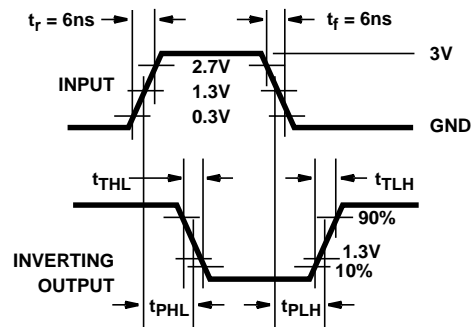
**NOTES:**

- $C_{PD}$  is used to determine the dynamic power consumption, per multiplexer.
- $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

### Test Circuits and Waveforms



**FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**



**FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9098401MEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD54HCT390F3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
CD74HC390E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC390EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HC390M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HC390MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390E	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT390EE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD74HCT390M	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390M96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390M96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390M96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390ME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390MG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390MT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390MTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT390MTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

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**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

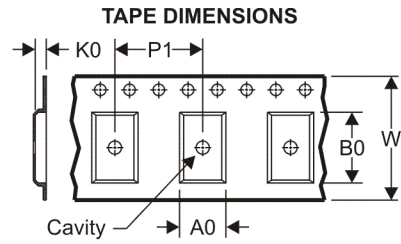
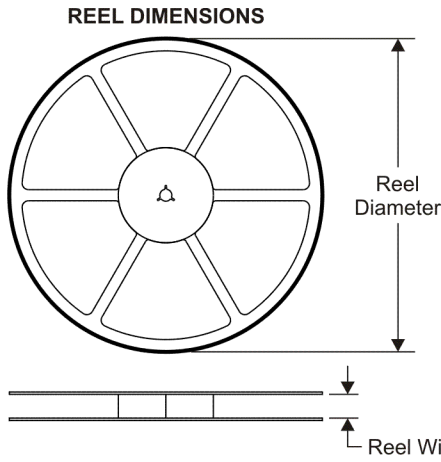
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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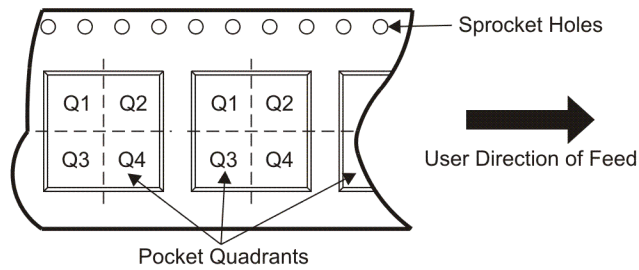
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**TAPE AND REEL INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC390M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT390M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC390M96	SOIC	D	16	2500	333.2	345.9	28.6
CD74HCT390M96	SOIC	D	16	2500	333.2	345.9	28.6

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

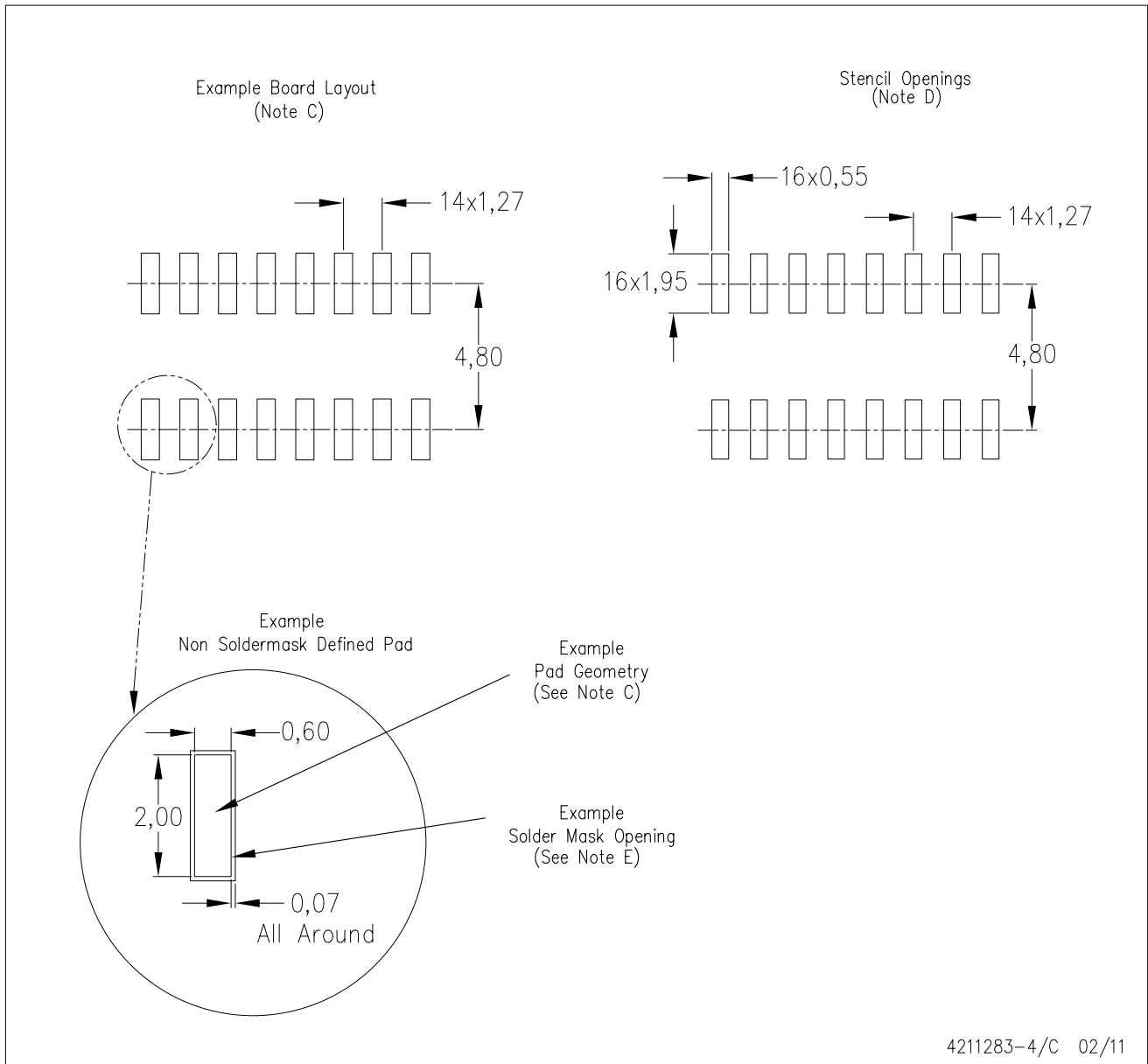


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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